# LH0032-200 Ultra Fast FET Operational Amplifier

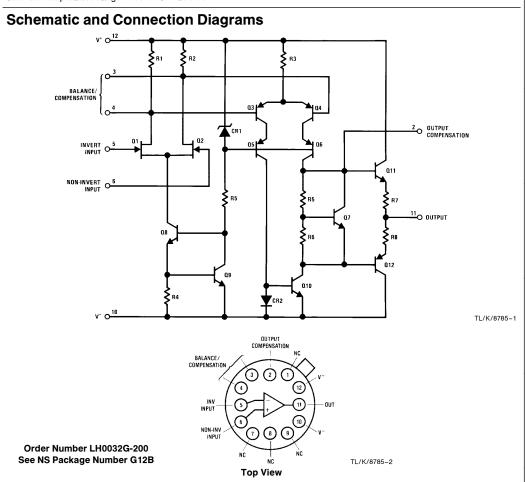
#### **General Description**

The LH0032-200 is a high slew rate, high input impedance differential operational amplifier suitable for diverse application in fast signal handling. The high allowable differential input voltage, ease of output clamping, and high output drive capability particularly suit it for comparator applications. It may be used in applications normally reserved for video amplifiers allowing the use of operational gain setting and frequency response shaping into the megahertz region.

The LH0032-200's wide bandwidth, high input impedance and high output capacity make it an ideal choice for applications such as summing amplifiers in high speed D to A's, buffers in data acquisition systems, and sample and hold circuits. Additional applications include high speed integrators and video amplifiers. The LH0032-200 is guaranteed over the temperature range  $-55^{\circ}\text{C}$  to  $+200^{\circ}\text{C}$ .

#### **Features**

- 200°C operation
- 500 V/µs slew rate
- 70 MHz bandwidth
- $10^{12}\Omega$  input impedance
- 5 mV max. input offset voltage
- FET input
- Offset null with single pot
- No compensation for gains above 50
- Peak output current to 100 mA
- Expected life in operation 160 hours



### **Absolute Maximum Ratings**

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

 $\begin{array}{lll} \text{Supply Voltage V}_S & \pm 18\text{V} \\ \text{Input Voltage} & \pm \text{V}_S \\ \text{Differential Input Voltage} & \pm 30\text{V or } \pm 2\text{V}_S \end{array}$ 

 $\begin{array}{llll} \mbox{Power Dissipation} & & & & & \\ T_A = 25^{\circ}\mbox{C} & & 1.5\mbox{W} \\ T_C = 25^{\circ}\mbox{C} & & 2.2\mbox{W} \\ \mbox{Operating Temperature Range} & -55^{\circ}\mbox{C to} + 200^{\circ}\mbox{C} \\ \mbox{Operating Junction Temperature Range} & 225^{\circ}\mbox{C} \\ \mbox{Storage Temperature Range} & -65^{\circ}\mbox{C to} + 225^{\circ}\mbox{C} \\ \mbox{Lead Temperature (soldering, 10 sec.)} & 260^{\circ}\mbox{C} \end{array}$ 

ESD rating is to be determined.

## DC Electrical Characteristics $V_S = \pm 15V, T_{MIN} \le T_A \le T_{MAX}$ unless otherwise noted

Symbol	Parameter	Test Conditions		Limits			Units
		1001	Min	Тур	Max	Omis	
Vos	Input Offset Voltage	$V_{IN} = 0$				25	mV
ΔV <sub>OS</sub> /ΔT	Average Offset Voltage Drift				25		μV/°C
los	Input Offset Current		$T_J = T_A = T_{MAX}$			150	nA
I <sub>B</sub>	Input Bias Current		$T_J = T_A = T_{MAX}$			250	nA
V <sub>INCM</sub>	Input Voltage Range			±10	±12		V
CMRR	Common Mode Rejection Ratio	$\Delta V_{IN} = 10V$	40	60		dB	
A <sub>VOL</sub>	Open-Loop Voltage Gain	$R_L = 1 k\Omega$ , $V_{OUT} = \pm 10V$		40	50		dB
Vo	Output Voltage Swing	$R_L = 1 k\Omega$		±9.0	± 13.5		V
Is	Power Supply Current	I <sub>O</sub> = 0 (Note 3)			18	26	mA
		Pulse			25		mA
PSRR	Power Supply Rejection Ratio	$\Delta V_{S} = 10V$		40	60		dB

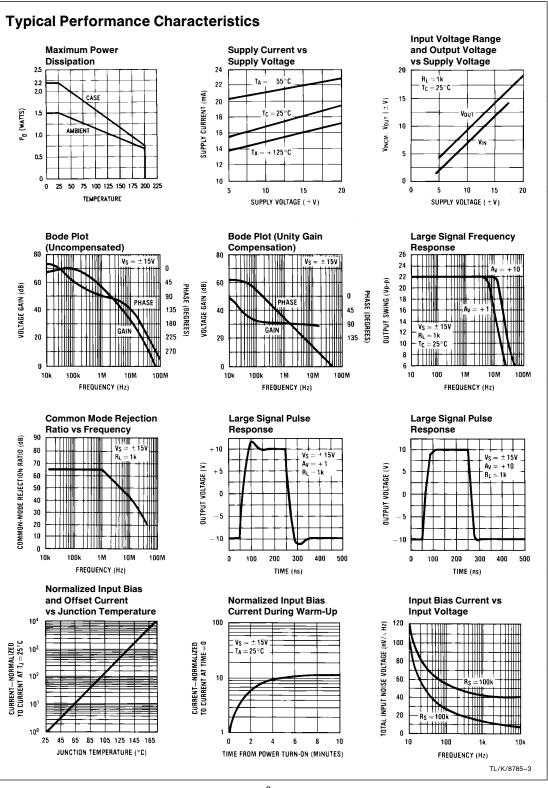
## AC Electrical Characteristics $V_S=\pm 15 V,\, R_L=1\,k\Omega,\, T_J=25^{\circ}C$

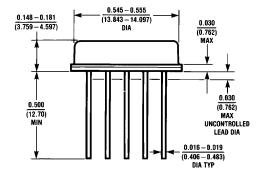
Symbol	Parameter	Conditions		Min	Тур	Max	Units
S <sub>R</sub>	Slew Rate	$A_{V} = +1$	$\Delta V_{IN} = 20V$	350	500		V/µs

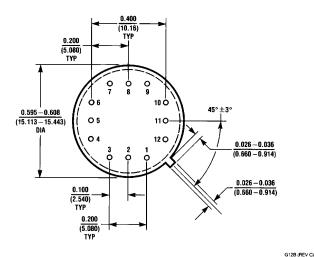
Note 1: In order to limit maximum junction temperature to  $\pm 225^{\circ}$ C it may be necessary to operate with  $V_S \le \pm 15V$  when  $T_A$  or  $T_C$  exceeds specific values depending on the  $P_D$  within the device package. Total  $P_D$  is the sum of quiescent and load-related dissipation. See Applications Notes AN277, "Applications of Wide-Band Buffer Amplifiers" and AN253, "High-Speed Operational-Amplifier Applications" for a discussion of load-related power dissipation.

Note 2: Specification is at 25°C junction temperature due to requirements of high-speed automatic testing. Actual values at operating temperature will exceed the value at T<sub>J</sub> = 25°C. When supply voltages are ±15V, no-load operating junction temperature may rise 40–60°C above ambient and more under load conditions. Accordingly, V<sub>OS</sub> may change one to several mV, and I<sub>B</sub> and I<sub>OS</sub> will change significantly during warm-up. Refer to I<sub>B</sub> and I<sub>OS</sub> vs. temperature graph for expected values.

Note 3: Measured in still air 7 minutes after application of power.







12-Lead Metal Can Package (G) Order Number LH0032G-200 NS Package Number G12B

#### LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



**National Semiconductor** National Semiconducto Corporation 1111 West Bardin Road Arlington, TX 76017 Tel: 1(800) 272-9959 Fax: 1(800) 737-7018

**National Semiconductor** Europe

Fax: (+49) 0-180-530 85 86 Fax: (+49) U-18U-35U oo oo Email: onjwge@tevm2.nsc.com Deutsch Tel: (+49) 0-180-530 85 85 English Tel: (+49) 0-180-532 78 32 Français Tel: (+49) 0-180-532 93 58 Italiano Tel: (+49) 0-180-534 16 80

**National Semiconductor** National Semiconductor Hong Kong Ltd. 13th Floor, Straight Block, Ocean Centre, 5 Canton Rd. Tsimshatsui, Kowloon Hong Kong Tel: (852) 2737-1600 Fax: (852) 2736-9960

National Semiconductor Japan Ltd.
Tel: 81-043-299-2309
Fax: 81-043-299-2408